



11-07-00

2811

PATENT
Attorney Docket No. 3818.1US (98-0887.1)

NOTICE OF EXPRESS MAILING

Express Mail Mailing Label Number: EL700254684US

Date of Deposit with USPS: November 6, 2000

Person making Deposit: Jared S. Turner

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Examiner: Unknown Group Art Unit No.: 2811
Applicant(s): Tongbi Jiang Filing date: April 5, 2000
Serial No.: 09/543,034 For (title): TAPE ATTACHMENT CHIP-ON-BOARD ASSEMBLIES
AND METHODS OF FABRICATING THE SAME

COMMUNICATION TRANSMITTAL

Commissioner for Patents
Washington, D.C. 20231

Sir:

Enclosed for filing in connection with the above-identified patent application, and submitted in the order listed, are:

- ☒ Postcard receipt acknowledgment (attached to the front of this transmittal).
☒ Duplicate copy of this transmittal sheet in the event that additional filing fees are required under 37 C.F.R. § 1.16. Any such fees may be charged to deposit account no. 20-1469.
☐ Check no. in the amount of \$ for the presentation of extra claims as calculated in the remarks section below.
☒ Preliminary amendment.
☐ Amendment or other communication in response to the non-final office action mailed.
☐ Amendment or other communication under 37 C.F.R. § 1.116 in response to the final office action mailed.
☐ Petition for Extension of Time in duplicate with check no. in the amount of \$.
☐ Verified statement(s) to establish small entity status under 37 C.F.R. § 1.9 and 37 C.F.R. § 1.27 signed by (or on behalf of).
☐ Information disclosure statement and information disclosure citation form PTO-1449 with copies of listed documents.

Remarks:

- ☐ An amendment has been made involving one or more claims in the application. The calculation to determine whether any additional fee is due is presented below.

	1	2	3		\$EXTRA	
Total claims	15	-	20	=	0 x 18.00 =	0.00
Indep. claims	2	-	3	=	0 x 78.00 =	0.00
First presentation of a multiple dep. claim (+260.00)						
SUBTOTAL						
Reduction for small entity - 50% of subtotal*						
TOTAL ADDITIONAL FEE (subtotal minus any reduction)						0.00

*Verified statement(s) must be attached to support this reduction if small entity status has not been previously established.

- 1 Claims remaining after amendment.
2 Highest number of claims previously paid for. Not less than 20 for total claims and 3 for independent claims.
3 Difference between claims remaining and highest number previously paid for. If less than zero, enter "0."

- ☒ The commissioner is authorized to charge any additional fees required but not submitted with any document or request requiring fee payment under 37 C.F.R. §§ 1.16 and 1.17 to deposit account no. 20-1469 during the entire pendency of this application.

Respectfully submitted,

James R. Duzan

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Date: November 6, 2000
Enclosures: As identified above
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THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Tongbi Jiang

Serial No.: 09/543,034

Filed: April 5, 2000

For: TAPE ATTACHMENT CHIP-ON-BOARD ASSEMBLIES AND METHODS OF FABRICATING THE SAME

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PRELIMINARY AMENDMENT

Commissioner for Patents
Washington, D.C. 20231

Sir:

Please revise the above-identified application as follows:

IN THE CLAIMS:

Please amend claims 1-3 and 15 as follows:

1. (Amended) A semiconductor die assembly comprising:
a semiconductor substrate having a first surface and a second surface, wherein said semiconductor substrate includes at least one opening defined [through said semiconductor substrate] therethrough between said semiconductor substrate first surface and said semiconductor substrate second surface;

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